

ABSTRACT OF THE DISCLOSURE

A stacked semiconductor device has a plurality of semiconductor elements mounted on the device in a stacked form. Each semiconductor element has a rectangular upper surface. A plurality of electrode pads is provided on the rectangular upper surface of the semiconductor element. In each semiconductor element, the electrode pads are arranged near two adjacent sides of the rectangular upper surface. A space for performing wire connection is made between two adjacent semiconductor elements. The adjacent semiconductor elements are joined to each other only by a die-bonding material without using any dummy element. The stacked semiconductor device can have increased number of electrode pads and increased functions compared to a conventional stacked semiconductor device.